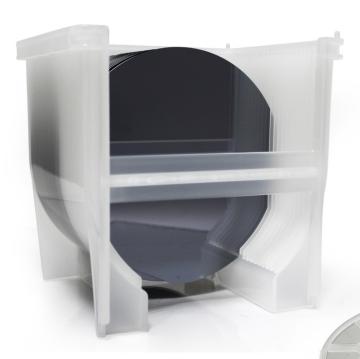


P Type N Type



Product Description

Silicon wafer-Silicon substrate is a thin slice of semiconductor material. It is used in electronics for the fabrication of integrated circuits and in photovoltaics for conventional, wafer-based solar cells. It is used as a support for the manufacture of microstructures by techniques such as etching, doping, deposition of other materials (epitaxy, sputtering, chemical vapor deposition, etc.) and photolithography.



- Totally customized
- Low and medium volumes
- Any diameter
- · Any orientations
- Any thickness

Diameter

1 inch 2 inch 3 inch 4 inch 5 inch 6 inch 8 inch 12 inch

Further diameters on request







Type & dopant

N - Type	P (Phosphorus), Sb (Antimony), As (Arsenic)
P-type	B (Boron)
Undoped	

Resistivity

Czochralski (CZ)	From 1 mΩ.cmto 150 mΩ.cm		
Float Zone (FZ)	Up to 10 mΩ.cm		
Orientation	<100>, <111>, <110>		
Tolerance	Standard: ± 0.5°		
Off orientation	Up to 40°		

Additional specification

	1"	2"	3"	4"	5"	6"			
TTV Std (µm)	<10	<10	<10	<10	<10	<10			
STIR Std (µm)	<2	<2	<2	<2	<2	<2			
GLOBAL TIR (µm)	<5	<5	<5	<5	<5	<5			
Roughness	On polished surface: <1nm								
Flatness	Onpolishedsurface:<1µm								

Surface	As Cut	Lapped	Etched	Single side polished	Double side polished
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Applications

- ✓ Manufacturing of semiconductors
- Laptops and Desktop computers
- Mobile smartphones, tablet-phones
- Wearable smart gadgets Home appliances
- Microchips
- Thin-film deposition process
- Calibrating instruments
- R&D and manufacturing
- Automobiles, aerospace and drone technology
- Al (Artificial Intelligence)
- MEMS fabrication
- Transistors, diodes, and rectifiers

- **Robotics**
- Solar cell
- Ics (Integrated Circuits)
- High-power applications (detectors and sensor devices)
- Opto-Electronic components









I www.nanoshel.com I sales@nanoshel.com









3422 Old Capitol Suit 1305 Wilmington DE - 19808 United States